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# 74VCX163245

## Low Voltage 16-Bit Dual Supply Translating Transceiver with 3-STATE Outputs

### Features

- Bidirectional interface between busses ranging from 1.65V to 3.6V
- Supports Live Insertion and Withdrawal<sup>(1)</sup>
- Static Drive ( $I_{OH}/I_{OL}$ )
  - $\pm 24\text{mA}$  @ 3.0V  $V_{CC}$
  - $\pm 18\text{mA}$  @ 2.3V  $V_{CC}$
  - $\pm 6\text{mA}$  @ 1.65V  $V_{CC}$
- Uses proprietary Quiet Series™ noise/EMI reduction circuitry
- Functionally compatible with 74 series 16245
- Latchup performance exceeds 300mA
- ESD performance:
  - Human Body Model >2000V
  - Machine model >200V
- Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA)

### Note:

1. To ensure the high impedance state during power up or power down,  $OE_n$  should be tied to  $V_{CCB}$  through a pull up resistor. The minimum value of the resistor is determined by the current sourcing capability of the driver.

### General Description

The VCX163245 is a dual supply, 16-bit translating transceiver that is designed for 2 way asynchronous communication between busses at different supply voltages by providing true signal translation. The supply rails consist of  $V_{CCA}$ , which is a higher potential rail operating at 2.3V to 3.6V and  $V_{CCB}$ , which is the lower potential rail operating at 1.65V to 2.7V. ( $V_{CCB}$  must be less than or equal to  $V_{CCA}$  for proper device operation). This dual supply design allows for translation from 1.8V to 2.5V busses to busses at a higher potential, up to 3.3V.

The Transmit/Receive ( $T/\bar{R}$ ) input determines the direction of data flow. Transmit (active-HIGH) enables data from A Ports to B Ports; Receive (active-LOW) enables data from B Ports to A Ports. The Output Enable ( $\overline{OE}$ ) input, when HIGH, disables both A and B Ports by placing them in a High-Z condition. The A Port interfaces with the higher voltage bus (2.7V to 3.3V); The B Port interfaces with the lower voltage bus (1.8V to 2.5V). Also the VCX163245 is designed so that the control pins ( $T/\bar{R}_n$ ,  $\overline{OE}_n$ ) are supplied by  $V_{CCB}$ .

The 74VCX163245 is suitable for mixed voltage applications such as notebook computers using a 1.8V CPU and 3.3V peripheral components. It is fabricated with an Advanced CMOS technology to achieve high speed operation while maintaining low CMOS power dissipation.

### Ordering Information

Order Number	Package Number	Package Description
74VCX163245G <sup>(2)(3)</sup>	BGA54A	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
74VCX163245MTD <sup>(3)</sup>	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

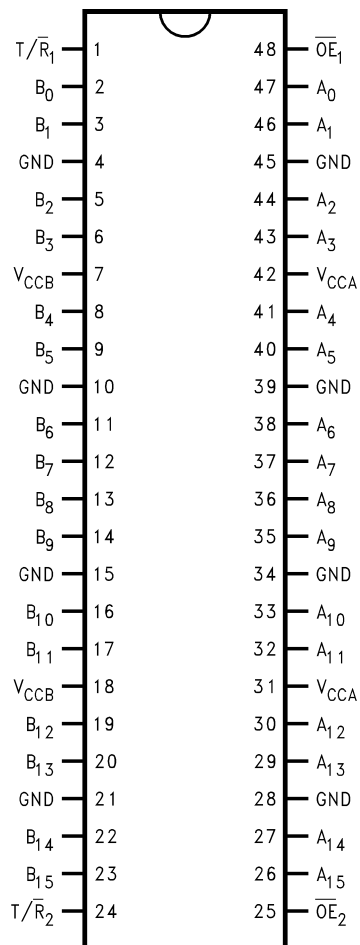
### Notes:

2. Ordering code "G" indicates Trays.
3. Device also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

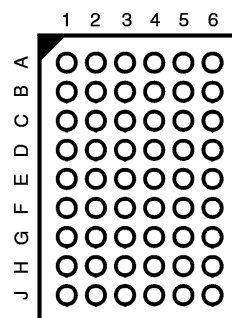
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## Connection Diagram

### Pin Assignment for TSSOP



### Pin Assignment for FBGA



(Top Thru View)

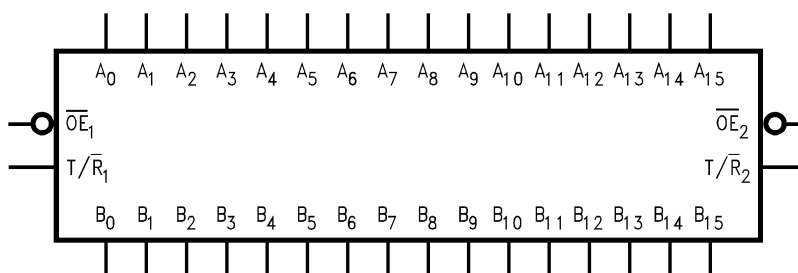
### FBGA Pin Assignments

	1	2	3	4	5	6
<b>A</b>	$B_0$	NC	$\overline{T/R}_1$	$\overline{OE}_1$	NC	$A_0$
<b>B</b>	$B_2$	$B_1$	NC	NC	$A_1$	$A_2$
<b>C</b>	$B_4$	$B_3$	$V_{CCB}$	$V_{CCA}$	$A_3$	$A_4$
<b>D</b>	$B_6$	$B_5$	GND	GND	$A_5$	$A_6$
<b>E</b>	$B_8$	$B_7$	GND	GND	$A_7$	$A_8$
<b>F</b>	$B_{10}$	$B_9$	GND	GND	$A_9$	$A_{10}$
<b>G</b>	$B_{12}$	$B_{11}$	$V_{CCB}$	$V_{CCA}$	$A_{11}$	$A_{12}$
<b>H</b>	$B_{14}$	$B_{13}$	NC	NC	$A_{13}$	$A_{14}$
<b>J</b>	$B_{15}$	NC	$\overline{T/R}_2$	$\overline{OE}_2$	NC	$A_{15}$

### Pin Descriptions

Pin Names	Description
$\overline{OE}_n$	Output Enable Input (Active LOW)
$\overline{T/R}_n$	Transmit/Receive Input
$A_0$ – $A_{15}$	Side A Inputs or 3-STATE Outputs
$B_0$ – $B_{15}$	Side B Inputs or 3-STATE Outputs
NC	No Connect

### Logic Diagram



### Truth Tables

Inputs		Outputs
$\overline{OE}_1$	$T/\overline{R}_1$	
L	L	Bus B <sub>0</sub> –B <sub>7</sub> Data to Bus A <sub>0</sub> –A <sub>7</sub>
L	H	Bus A <sub>0</sub> –A <sub>7</sub> Data to Bus B <sub>0</sub> –B <sub>7</sub>
H	X	HIGH Z State on A <sub>0</sub> –A <sub>7</sub> , B <sub>0</sub> –B <sub>7</sub>

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial (HIGH or LOW, inputs may not float)

Z = High Impedance

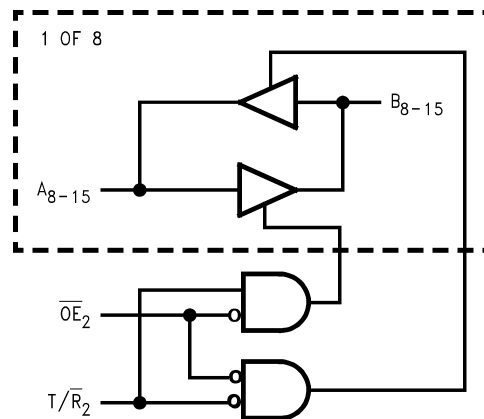
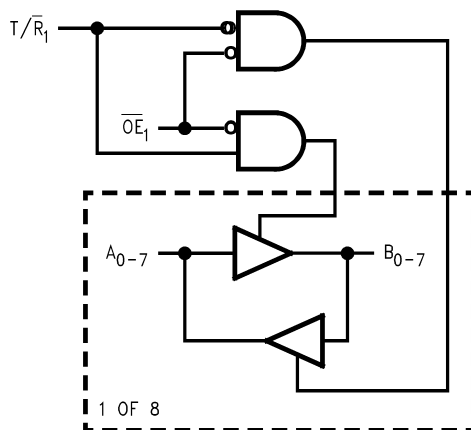
Inputs		Outputs
$\overline{OE}_2$	$T/\overline{R}_2$	
L	L	Bus B <sub>8</sub> –B <sub>15</sub> Data to Bus A <sub>8</sub> –A <sub>15</sub>
L	H	Bus A <sub>8</sub> –A <sub>15</sub> Data to Bus B <sub>8</sub> –B <sub>15</sub>
H	X	HIGH-Z State on A <sub>8</sub> –A <sub>15</sub> , B <sub>8</sub> –B <sub>15</sub>

### VCX163245 Translator Power Up Sequence Recommendations

To guard against power up problems, some simple guidelines need to be adhered to. The VCX163245 is designed so that the control pins ( $T/\overline{R}_n$ ,  $\overline{OE}_n$ ) are supplied by  $V_{CCB}$ . Therefore the first recommendation is to begin by powering up the control side of the device,  $V_{CCB}$ . The  $\overline{OE}_n$  control pins should be ramped with or ahead of  $V_{CCB}$ , this will guard against bus contentions and oscillations as all A Port and B Port outputs will be disabled. To ensure the high impedance state during power up or power down,  $\overline{OE}_n$  should be tied to  $V_{CCB}$  through a pull up resistor. The minimum value of the resistor is determined by the current sourcing capability of the driver. Second, the  $T/\overline{R}_n$  control pins should be

placed at logic LOW (0V) level, this will ensure that the B-side bus pins are configured as inputs to help guard against bus contention and oscillations. B-side Data Inputs should be driven to a valid logic level (0V or  $V_{CCB}$ ), this will prevent excessive current draw and oscillations.  $V_{CCA}$  can then be powered up after  $V_{CCB}$ , however  $V_{CCA}$  must be greater than or equal to  $V_{CCB}$  to ensure proper device operation. Upon completion of these steps the device can then be configured for the users desired operation. Following these steps will help to prevent possible damage to the translator device as well as other system components.

### Logic Diagrams



Please note that these diagrams are provided only for the understanding of logic operations and should not be used to estimate propagation delays.

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
$V_{CCA}$	Supply Voltage	-0.5V to +4.6V
$V_{CCB}$		-0.5V to $V_{CCA}$
$V_I$	DC Input Voltage	-0.5V to +4.6V
$V_{I/O}$	DC Output Voltage Outputs 3-STATE $A_n$ Output Active <sup>(4)</sup> $B_n$ Output Active <sup>(4)</sup>	-0.5V to +4.6V -0.5V to $V_{CCA} + 0.5V$ -0.5V to $V_{CCB} + 0.5V$
$I_{IK}$	DC Input Diode Current, $V_I < 0V$	-50mA
$I_{OK}$	DC Output Diode Current $V_O < 0V$ $V_O > V_{CC}$	-50mA +50mA
$I_{OH}/I_{OL}$	DC Output Source/Sink Current	±50mA
	DC $V_{CC}$ or Ground Current	±100mA
$I_{CC}$ or Ground	Supply Pin	
$T_{STG}$	Storage Temperature	-65°C to +150°C

## Recommended Operating Conditions<sup>(5)</sup>

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
$V_{CCA}$	Power Supply <sup>(6)</sup>	2.3V to 3.6V
$V_{CCB}$		1.65V to 2.7V
$V_I$	Input Voltage () @ $\overline{OE}$ , $T/\overline{R}$	0V to $V_{CCB}$
$V_{I/O}$	Input/Output Voltage () $A_n$ $B_n$	0V to $V_{CCA}$ 0V to $V_{CCB}$
$I_{OH}/I_{OL}$	Output Current in $I_{OH}/I_{OL}$ $V_{CCA} = 3.0V$ to 3.6V $V_{CCA} = 2.3V$ to 2.7V $V_{CCB} = 2.3V$ to 2.7V $V_{CCB} = 1.65V$ to 1.95V	±24mA ±18mA ±18mA ±6mA
$T_A$	Free Air Operating Temperature	-40°C to +85°C
$\Delta t/\Delta V$	Minimum Input Edge Rate, $V_{IN} = 0.8V$ to 2.0V, $V_{CC} = 3.0V$	10ns/V

### Notes:

- $I_O$  Absolute Maximum Rating must be observed.
- Unused inputs or I/O pins must be held HIGH or LOW. They may not float.
- Operation requires:  $V_{CCB} \leq V_{CCA}$

**DC Electrical Characteristics** ( $1.65V < V_{CCB} \leq 1.95V$ ,  $2.3V < V_{CCA} \leq 2.7V$ )

Symbol	Parameter	$V_{CCB}$ (V)	$V_{CCA}$ (V)	Conditions	Min.	Max.	Units
$V_{IHA}$	HIGH Level Input Voltage	$A_n$	1.65–1.95	2.3–2.7		1.6	V
$V_{IHB}$		$B_n, \overline{T/R}, \overline{OE}$	1.65–1.95	2.3–2.7		$0.65 \times V_{CCB}$	V
$V_{ILA}$	LOW Level Input Voltage	$A_n$	1.65–1.95	2.3–2.7		0.7	V
$V_{ILB}$		$B_n, \overline{T/R}, \overline{OE}$	1.65–1.95	2.3–2.7		$0.35 \times V_{CCB}$	V
$V_{OHA}$	HIGH Level Output Voltage		1.65–1.95	2.3–2.7	$I_{OH} = -100\mu A$	$V_{CCA} - 0.2$	V
			1.65	2.3–2.7	$I_{OH} = -18mA$	1.7	
$V_{OHB}$	HIGH Level Output Voltage		1.65–1.95	2.3–2.7	$I_{OH} = -100\mu A$	$V_{CCB} - 0.2$	V
			1.65–1.95	2.3	$I_{OH} = -6mA$	1.25	
$V_{OLA}$	Low Level Output Voltage		1.65–1.95	2.3–2.7	$I_{OL} = 100\mu A$	0.2	V
			1.65	2.3–2.7	$I_{OL} = 18mA$	0.6	
$V_{OLB}$	Low Level Output Voltage		1.65–1.95	2.3–2.7	$I_{OL} = 100\mu A$	0.2	V
			1.65–1.95	2.3	$I_{OL} = 6mA$	0.3	
$I_I$	Input Leakage Current @ $\overline{OE}$ , $\overline{T/R}$	1.65–1.95	2.3–2.7	$0V \leq V_I \leq 3.6V$		$\pm 5.0$	$\mu A$
$I_{OZ}$	3-STATE Output Leakage	1.65–1.95	2.3–2.7	$0V \leq V_O \leq 3.6V$ , $\overline{OE} = V_{CCB}$ , $V_I = V_{IH}$ or $V_{IL}$		$\pm 10$	$\mu A$
$I_{OFF}$	Power Off Leakage Current	0	0	$0 \leq (V_I, V_O) \leq 3.6V$		10	$\mu A$
$I_{CCA}/I_{CCB}$	Quiescent Supply Current, per supply, $V_{CCA} / V_{CCB}$		1.65–1.95	2.3–2.7	$A_n = V_{CCA}$ or GND, $B_n, \overline{OE}$ , & $\overline{T/R} = V_{CCB}$ or GND	20	$\mu A$
			1.65–1.95	2.3–2.7	$V_{CCA} \leq A_n \leq 3.6V$ , $V_{CCB} \leq B_n, \overline{OE}$ , $\overline{T/R} \leq 3.6V$	$\pm 20$	$\mu A$
$\Delta I_{CC}$	Increase in $I_{CC}$ per Input, $B_n, \overline{T/R}, \overline{OE}$	1.65–1.95	2.3–2.7	$V_I = V_{CCB} - 0.6V$		750	$\mu A$
	Increase in $I_{CC}$ per Input, $A_n$	1.65–1.95	2.3–2.7	$V_I = V_{CCA} - 0.6V$		750	$\mu A$

**DC Electrical Characteristics** ( $1.65V < V_{CCB} \leq 1.95V$ ,  $3.0V < V_{CCA} \leq 3.6V$ )

Symbol	Parameter	$V_{CCB}$ (V)	$V_{CCA}$ (V)	Conditions	Min.	Max.	Units
$V_{IHA}$	HIGH Level Input Voltage	$A_n$	1.65–1.95	3.0–3.6		2.0	V
$V_{IHB}$		$B_n, \overline{T/R}, \overline{OE}$	1.65–1.95	3.0–3.6		$0.65 \times V_{CCB}$	V
$V_{ILA}$	LOW Level Input Voltage	$A_n$	1.65–1.95	3.0–3.6		0.8	V
$V_{ILB}$		$B_n, \overline{T/R}, \overline{OE}$	1.65–1.95	3.0–3.6		$0.35 \times V_{CCB}$	V
$V_{OHA}$	HIGH Level Output Voltage		1.65–1.95	3.0–3.6	$I_{OH} = -100\mu A$	$V_{CCA} - 0.2$	V
			1.65	3.0–3.6	$I_{OH} = -24mA$	2.2	
$V_{OHB}$	HIGH Level Output Voltage		1.65–1.95	3.0–3.6	$I_{OH} = -100\mu A$	$V_{CCA} - 0.2$	V
			1.65–1.95	3.0	$I_{OH} = -6mA$	1.25	
$V_{OLA}$	LOW Level Output Voltage		1.65–1.95	3.0–3.6	$I_{OL} = 100\mu A$	0.2	V
			1.65	3.0–3.6	$I_{OL} = 24mA$	0.55	
$V_{OLB}$	LOW Level Output Voltage		1.65–1.95	3.0–3.6	$I_{OL} = 100\mu A$	0.2	V
			1.65–1.95	3.0	$I_{OL} = 6mA$	0.3	
$I_I$	Input Leakage Current @ $\overline{OE}$ , $\overline{T/R}$	1.65–1.95	3.0–3.6	$0V \leq V_I \leq 3.6V$		$\pm 5.0$	$\mu A$
$I_{OZ}$	3-STATE Output Leakage	1.65–1.95	3.0–3.6	$0V \leq V_O \leq 3.6V$ , $\overline{OE} = V_{CCB}$ , $V_I = V_{IH}$ or $V_{IL}$		$\pm 10$	$\mu A$
$I_{OFF}$	Power OFF Leakage Current	0	0	$0 \leq (V_I, V_O) \leq 3.6V$		10	$\mu A$
$I_{CCA}/I_{CCB}$	Quiescent Supply Current, per supply, $V_{CCA}/V_{CCB}$		1.65–1.95	3.0–3.6	$A_n = V_{CCA}$ or GND, $B_n, \overline{OE}$ , & $\overline{T/R} = V_{CCB}$ or GND	20	$\mu A$
			1.65–1.95	3.0–3.6	$V_{CCA} \leq A_n \leq 3.6V$ , $V_{CCB} \leq B_n, \overline{OE}$ , $\overline{T/R} \leq 3.6V$	$\pm 20$	
$\Delta I_{CC}$	Increase in $I_{CC}$ per Input, $B_n, \overline{T/R}, \overline{OE}$ ,	1.65–1.95	3.0–3.6	$V_I = V_{CCB} - 0.6V$		750	$\mu A$
	Increase in $I_{CC}$ per Input, $A_n$	1.65–1.95	3.0–3.6	$V_I = V_{CCA} - 0.6V$		750	

**DC Electrical Characteristics** ( $2.3V < V_{CCB} \leq 2.7V$ ,  $3.0V \leq V_{CCA} \leq 3.6V$ )

Symbol	Parameter	$V_{CCB}$ (V)	$V_{CCA}$ (V)	Conditions	Min.	Max.	Units
$V_{IHA}$	HIGH Level Input Voltage	$A_n$	2.3–2.7	3.0–3.6		2.0	V
$V_{IHB}$		$B_n, T/\bar{R}, \overline{OE}$	2.3–2.7	3.0–3.6		1.6	V
$V_{ILA}$	LOW Level Input Voltage	$A_n$	2.3–2.7	3.0–3.6		0.8	V
$V_{ILB}$		$B_n, T/\bar{R}, \overline{OE}$	2.3–2.7	3.0–3.6		0.7	V
$V_{OHA}$	HIGH Level Output Voltage		2.3–2.7	3.0–3.6	$I_{OH} = -100\mu A$	$V_{CCA} - 0.2$	V
			2.3	3.0–3.6	$I_{OH} = -24mA$	2.2	
$V_{OHB}$	HIGH Level Output Voltage		2.3–2.7	3.0–3.6	$I_{OH} = -100\mu A$	$V_{CCB} - 0.2$	V
			2.3–2.7	3.0	$I_{OH} = -18mA$	1.7	
$V_{OLA}$	LOW Level Output Voltage		2.3–2.7	3.0–3.6	$I_{OL} = 100\mu A$	0.2	V
			2.3	3.0–3.6	$I_{OL} = 24mA$	0.55	
$V_{OLB}$	LOW Level Output Voltage		2.3–2.7	3.0–3.6	$I_{OL} = 100\mu A$	0.2	V
			2.3–2.7	3.0	$I_{OL} = 18mA$	0.6	
$I_I$	Input Leakage Current @ $\overline{OE}$ , $T/\bar{R}$	2.3–2.7	3.0–3.6	$0V \leq V_I \leq 3.6V$		$\pm 5.0$	$\mu A$
$I_{OZ}$	3-STATE Output Leakage @ $A_n$	2.3–2.7	3.0–3.6	$0V \leq V_O \leq 3.6V$ , $\overline{OE} = V_{CCA}$ , $V_I = V_{IH}$ or $V_{IL}$		$\pm 10$	$\mu A$
$I_{OFF}$	Power OFF Leakage Current	0	0	$0 \leq (V_I, V_O) \leq 3.6V$		10	$\mu A$
$I_{CCA}/I_{CCB}$	Quiescent Supply Current, per supply, $V_{CCA}/V_{CCB}$		2.3–2.7	3.0–3.6	$A_n = V_{CCA}$ or GND, $B_n, \overline{OE}$ , & $T/\bar{R} = V_{CCB}$ or GND	20	$\mu A$
			2.3–2.7	3.0–3.6	$V_{CCA} \leq A_n \leq 3.6V$ , $V_{CCB} \leq B_n, \overline{OE}$ , $T/\bar{R} \leq 3.6V$	$\pm 20$	$\mu A$
$\Delta I_{CC}$	Increase in $I_{CC}$ per Input, $B_n, T/\bar{R}, \overline{OE}$	2.3–2.7	3.0–3.6	$V_I = V_{CCB} - 0.6V$		750	$\mu A$
	Increase in $I_{CC}$ per Input, $A_n$	2.3–2.7	3.0–3.6	$V_I = V_{CCA} - 0.6V$		750	$\mu A$



## AC Electrical Characteristics

Symbol	Parameter	$T_A = -40^\circ\text{C to } +85^\circ\text{C}, C_L = 30\text{ pF}, R_L = 500\Omega$						Units
		$V_{CCB} = 1.65\text{V to } 1.95\text{V}, V_{CCA} = 2.3\text{V to } 2.7\text{V}$		$V_{CCB} = 1.65\text{V to } 1.95\text{V}, V_{CCA} = 3.0\text{V to } 3.6\text{V}$		$V_{CCB} = 2.3\text{V to } 2.7\text{V}, V_{CCA} = 3.0\text{V to } 3.6\text{V}$		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{PHL}, t_{PLH}$	Propagation Delay, A to B	1.5	5.8	1.5	6.2	0.8	4.4	ns
$t_{PHL}, t_{PLH}$	Propagation Delay, B to A	0.8	5.5	0.6	5.1	0.6	4.0	ns
$t_{PZL}, t_{PZH}$	Output Enable Time, OE to B	1.5	8.3	1.5	8.2	0.8	4.6	ns
$t_{PZL}, t_{PZH}$	Output Enable Time, OE to A	0.8	5.3	0.6	5.1	0.6	4.0	ns
$t_{PLZ}, t_{PHZ}$	Output Disable Time, OE to B	0.8	4.6	0.8	4.5	0.8	4.4	ns
$t_{PLZ}, t_{PHZ}$	Output Disable Time, OE to A	0.8	5.2	0.6	5.6	0.6	4.8	ns
$t_{osHL}, t_{osLH}$	Output to Output Skew <sup>(7)</sup>		0.05		0.5		0.75	ns

## Note:

7. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW ( $t_{osHL}$ ) or LOW-to-HIGH ( $t_{osLH}$ ).

## Dynamic Switching Characteristics

Symbol	Parameter	$V_{CCB}$ (V)	$V_{CCA}$ (V)	Conditions	$T_A = +25^\circ\text{C}$ Typical	Units
$V_{OLP}$	Quiet Output Dynamic Peak $V_{OL}$ , A to B	1.8	2.5	$C_L = 30\text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0\text{V}$	0.25	V
		1.8	3.3		0.25	
		2.5	3.3		0.6	
$V_{OLP}$	Quiet Output Dynamic Peak $V_{OL}$ , B to A	1.8	2.5	$C_L = 30\text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0\text{V}$	0.6	V
		1.8	3.3		0.8	
		2.5	3.3		0.8	
$V_{OLV}$	Quiet Output Dynamic Valley $V_{OL}$ , A to B	1.8	2.5	$C_L = 30\text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0\text{V}$	-0.25	V
		1.8	3.3		-0.25	
		2.5	3.3		-0.6	
$V_{OLV}$	Quiet Output Dynamic Valley $V_{OL}$ , B to A	1.8	2.5	$C_L = 30\text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0\text{V}$	-0.6	V
		1.8	3.3		-0.8	
		2.5	3.3		-0.8	
$V_{OHV}$	Quiet Output Dynamic Valley $V_{OH}$ , A to B	1.8	2.5	$C_L = 30\text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0\text{V}$	1.3	V
		1.8	3.3		1.3	
		2.5	3.3		1.7	
$V_{OHV}$	Quiet Output Dynamic Valley $V_{OH}$ , B to A	1.8	2.5	$C_L = 30\text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0\text{V}$	1.7	V
		1.8	3.3		2.0	
		2.5	3.3		2.0	

## Capacitance

Symbol	Parameter	Conditions	T <sub>A</sub> = +25°C	Units
C <sub>IN</sub>	Input Capacitance	V <sub>CCB</sub> = 2.5V, V <sub>CCA</sub> = 3.3V, V <sub>I</sub> = 0V or V <sub>CCA/B</sub>	5	pF
C <sub>I/O</sub>	Input/Output Capacitance	V <sub>CCB</sub> = 2.5V, V <sub>CCA</sub> = 3.3V, V <sub>I</sub> = 0V or V <sub>CCA/B</sub>	6	pF
C <sub>PD</sub>	Power Dissipation Capacitance	V <sub>CCB</sub> = 2.5V, V <sub>CCA</sub> = 3.3V, V <sub>I</sub> = 0V or V <sub>CCA/B</sub> , f = 10MHz	20	pF

## AC Loading and Waveforms

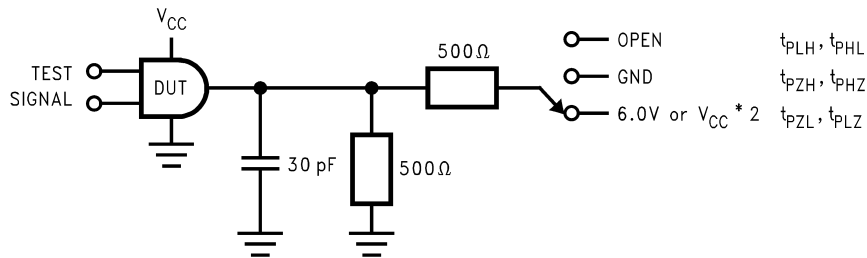


Figure 1. AC Test Circuit

Test	Switch
t <sub>PLH</sub> , t <sub>PHL</sub>	OPEN
t <sub>PZL</sub> , t <sub>PLZ</sub>	6V at V <sub>CC</sub> = 3.3 ± 0.3V; V <sub>CC</sub> × 2 at V <sub>CC</sub> = 2.5 ± 0.2V; 1.8V ± 0.15V
t <sub>PZH</sub> , t <sub>PHZ</sub>	GND

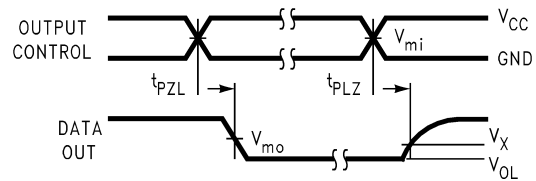


Figure 4. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic  
t<sub>R</sub> = t<sub>F</sub> ≤ 2.0 ns, 10% to 90%

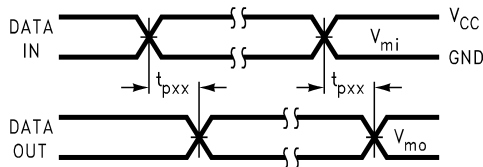


Figure 2. Waveform for Inverting and Non-inverting Functions  
t<sub>R</sub> = t<sub>F</sub> ≤ 2.0 ns, 10% to 90%

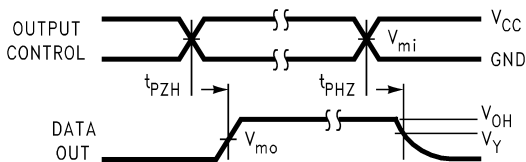
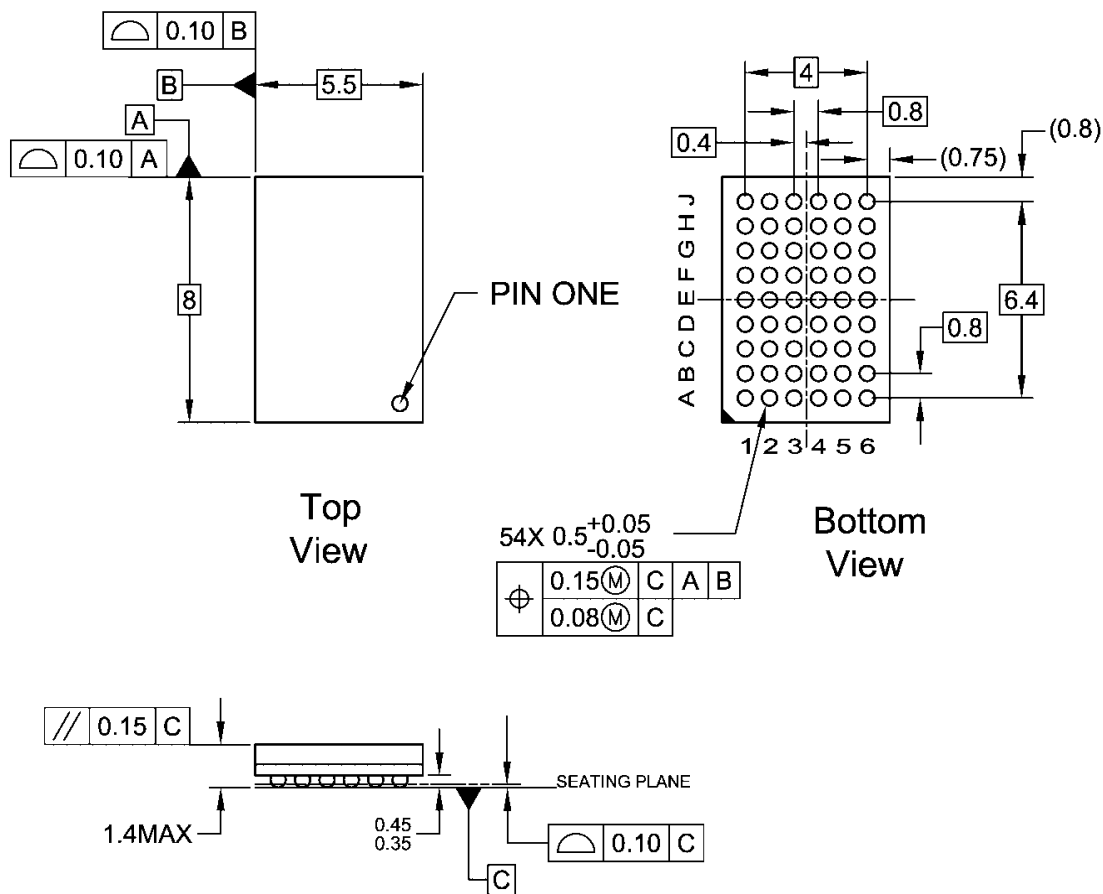


Figure 3. 3-STATE Output High Enable and Disable Times for Low Voltage Logic  
t<sub>R</sub> = t<sub>F</sub> ≤ 2.0 ns, 10% to 90%

Symbol	V <sub>CC</sub>		
	3.3V ± 0.3V	2.5V ± 0.2V	1.8V ± 0.15V
V <sub>mi</sub>	1.5V	V <sub>CC</sub> / 2	V <sub>CC</sub> / 2
V <sub>mo</sub>	1.5V	V <sub>CC</sub> / 2	V <sub>CC</sub> / 2
V <sub>X</sub>	V <sub>OL</sub> + 0.3V	V <sub>OL</sub> + 0.15V	V <sub>OL</sub> + 0.15V
V <sub>Y</sub>	V <sub>OH</sub> - 0.3V	V <sub>OH</sub> - 0.15V	V <sub>OH</sub> - 0.15V

### Physical Dimensions

Dimensions are in millimeters unless otherwise noted.



**NOTES:**

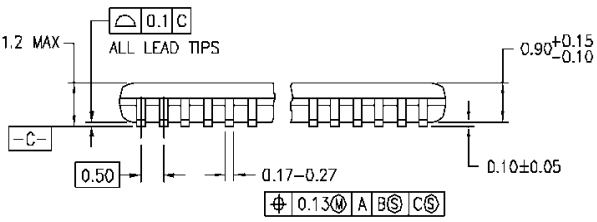
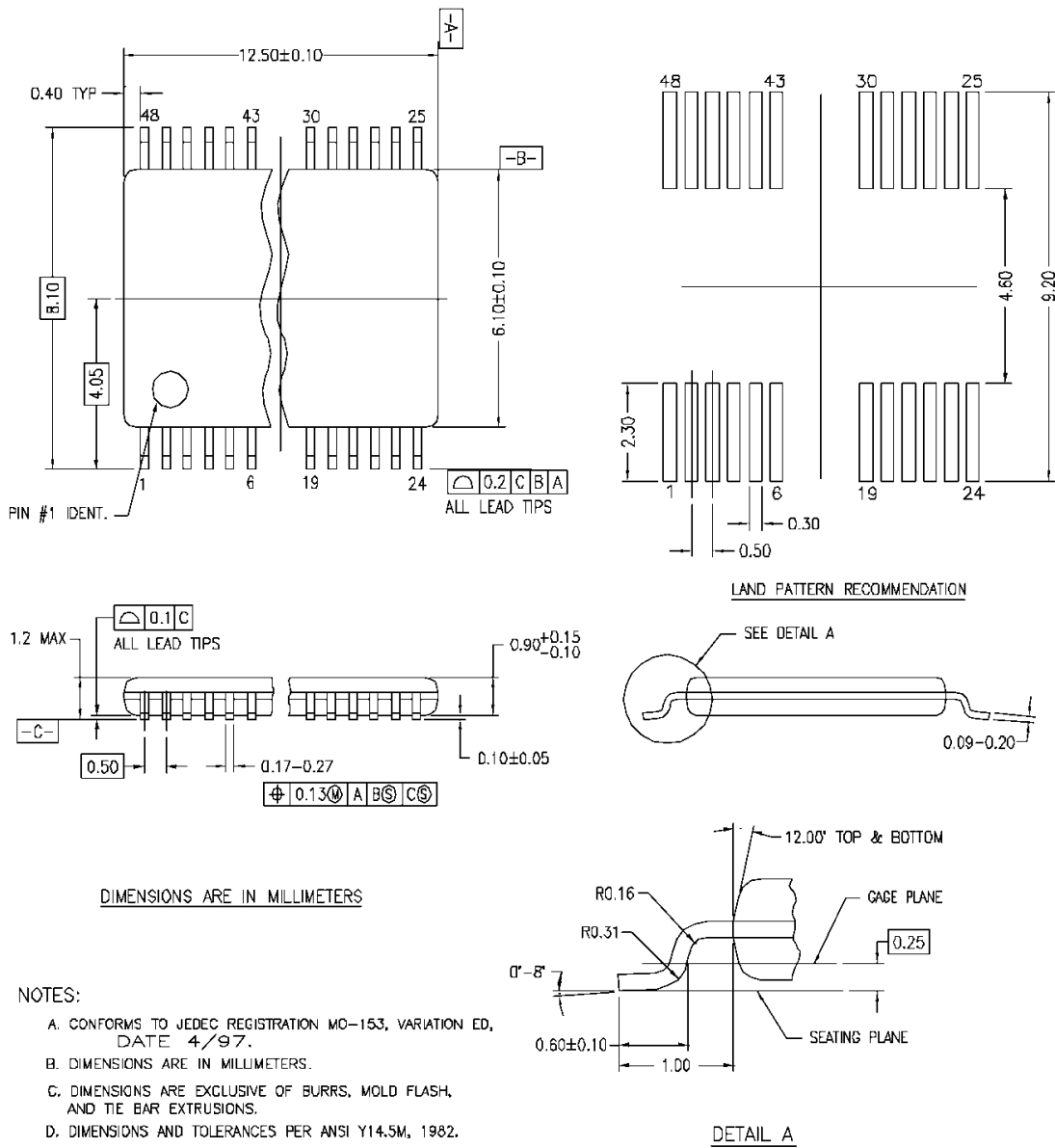
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- B. ALL DIMENSIONS IN MILLIMETERS
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)  
.35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
- D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA54ArevD

**Figure 5. 54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA54A**

### Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.



DIMENSIONS ARE IN MILLIMETERS

**NOTES:**

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ED, DATE 4/97.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.


MTD48REVC

**Figure 6. 48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48**



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